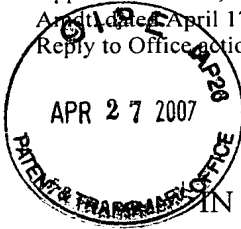


Appl. No. 10/776,477  
Filed April 17, 2007  
Reply to Office action of January 17, 2007

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:

LLERA et al.

Application No: 10/776,477

Filed: Feb. 10, 2004

For: Method for Applying  
Downward Force on Wafer During CMP  
(Amended)

Group Art Unit:

Examiner: Anthony Ojini

Atty. Docket No:

Date: April 17, 2007

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450 on April 17, 2007.

Signed: \_\_\_\_\_

Al Penilla

AMENDMENT

Honorable Commissioner for Patents  
Alexandria VA 22313-1450

Dear Sir:

In response to the Office Action dated January 17, 2007, the term to respond extends to April 17, 2007. Please enter this amendment and remarks.

**Amendment to the title** is reflected on page 2 of this paper.

**Amendments to the claims** are reflected in the listing of claims which begin on page 3 of this paper.

**Remarks/Arguments** begin on page 8 of this paper.

05/01/2007 FMEK11 00000004 500805 10776477

01 FC:1201 400.00 DA

**TITLE**

Please amend the title to:

--Method for applying downward force on a wafer during CMP--